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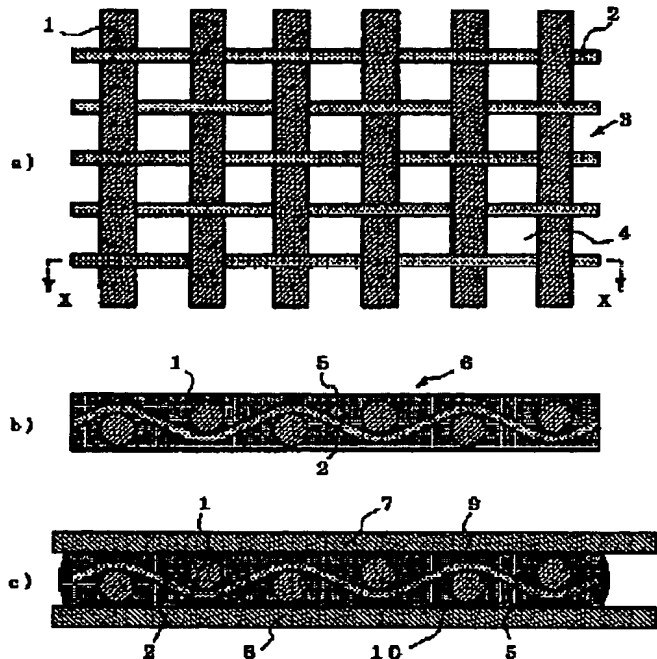
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TITLE : ADHEIVE ANISOTROPIC
CONDUCTIVE HEET AND
CONNECTING METHOD FOR
ELECTRIC CIRCUIT MEMBER UING IT



ABSTRACT : **PURPOSE:** To prevent leak failure or conduction defectiveness at the time of adhering work to improve reliability, by forming a mesh, of a conductive wire as a warp and of an insulating wire as a weft, and filling the gaps of a mesh with insulating adhesive.

CONSTITUTION: A mesh 3 is woven of conductive warps 1 and insulating wefts 2, and gaps 4 of the mesh are filled with insulating adhesive 5 to manufacture an adhesive anisotropic conductive sheet 6. The conductive wire can be surely fixed to a given position because the mesh is formed of the conductive wires and the insulating wires. When the sheet 6 is nipped between the respective linearly parallel electrodes 9 and 10, mutually faced in parallel, of connected electric circuit members 7 and 8 to be pressed, the bending part of the conductive wire exposed upward contacts the electrode 9 on the member 7, and the bending part of the conductive wire exposed downward contacts the electrode 10 on the member 8 to electrically connect the electrodes opposed via the conductive wire. Consequently the contact surface of the electrode is increased, obtaining low resistance. Also a retaining part is eliminated, taking a good effect on lightening in weight and thinning of electric equipment.

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